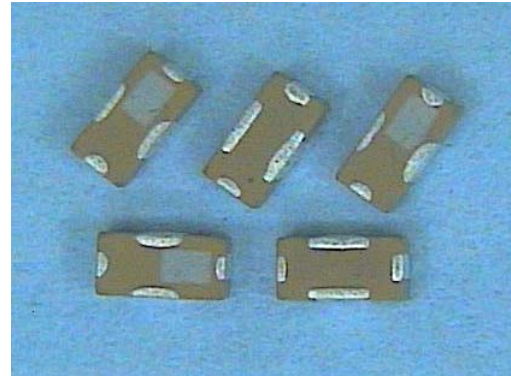


BF 1608 Series

Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.



Applications

- ❖ 0.8 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, Hyper-LAN, etc.

Specifications

Part Number	Freq. Range (MHz)	Insertion Loss @ BW (dB)	VSWR @ BW	Frequency	Attenuation (dB)
BF1608-L2R4DAA_	2400 ~ 2500	1.7 max.	2.0 max.	880 ~ 915MHz	30 min.
				1710 ~ 1785MHz	30 min.
				1850 ~ 1910MHz	25 min.
				4800 ~ 5000MHz	25 min.
				7200 ~ 7500MHz	15 min.

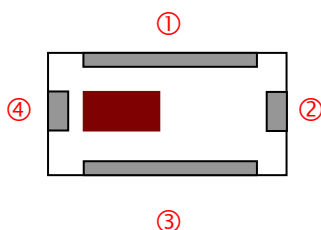
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH
 Storage Period : 12 months max.*
 *12 months in vacuum sealed bag and 1 week after opened. Please keep unused parts in vacuum sealed bags.
 Solder Paste : SAC 305 type is recommended.
 Power Capacity : 2W max.

Part Number

BF **1608** - **L** **2R4** **DAA** **□** **/LF**
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	BF : Band-Pass Filter	② Dimensions (L x W)	1.6 x 0.8 mm
③ Material Code	L	④ Frequency Range	2R4=2400MHz
⑤ Specification Code	DAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

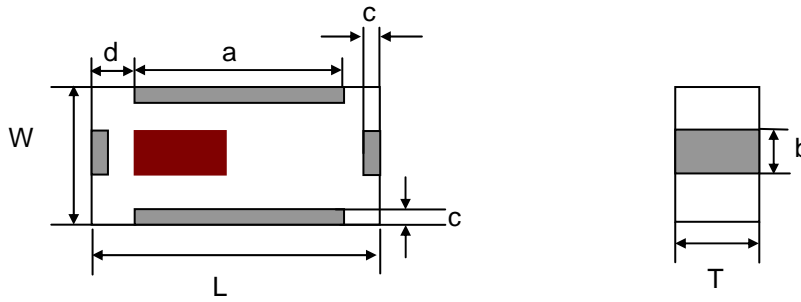
Terminal Configuration



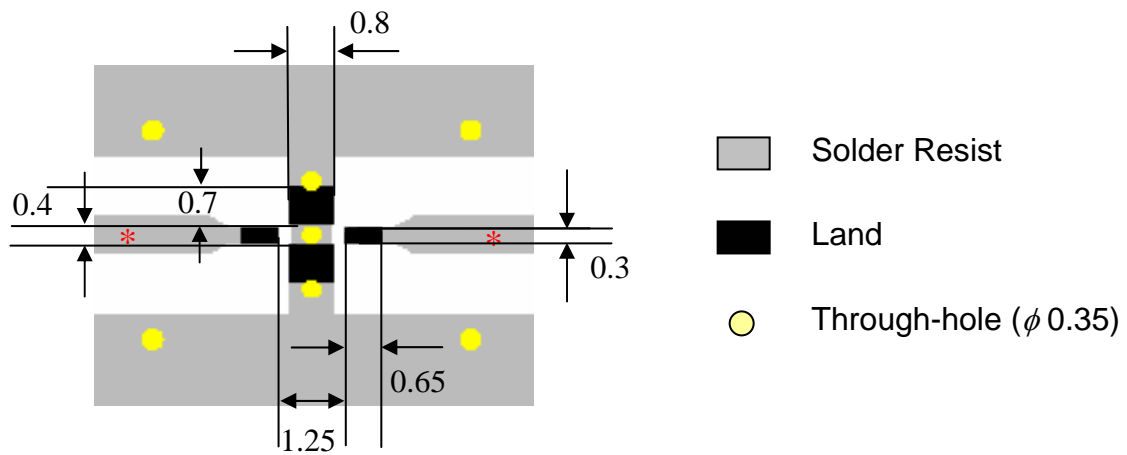
No.	Terminal Name	No.	Terminal Name
①	GND	③	GND
②	IN/OUT	④	IN/OUT

Dimensions and Recommended PC Board Pattern

Unit : mm

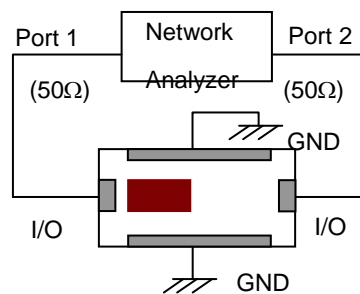


Mark	L	W	T	a	b	c	d
Dimensions	1.6 ± 0.10	0.8 ± 0.10	0.6 ± 0.10	0.7 ± 0.15	0.3 ± 0.10	0.15 ± 0.10	0.45 ± 0.15

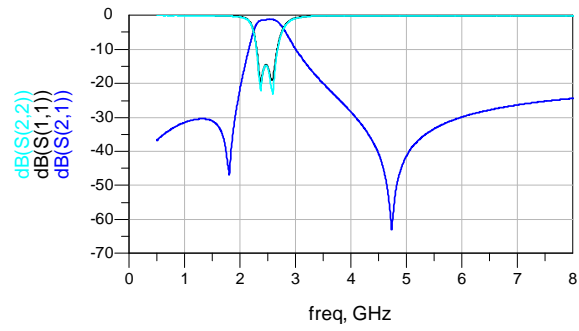


* Line width should be designed to match 50 characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25°C)

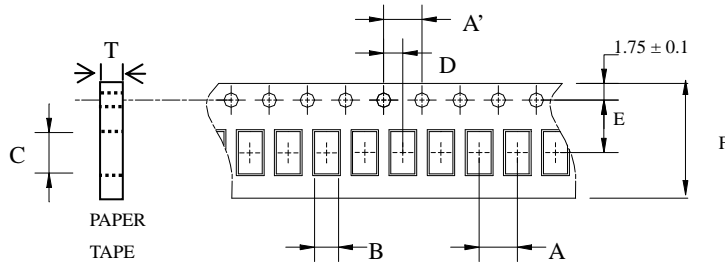


Notes

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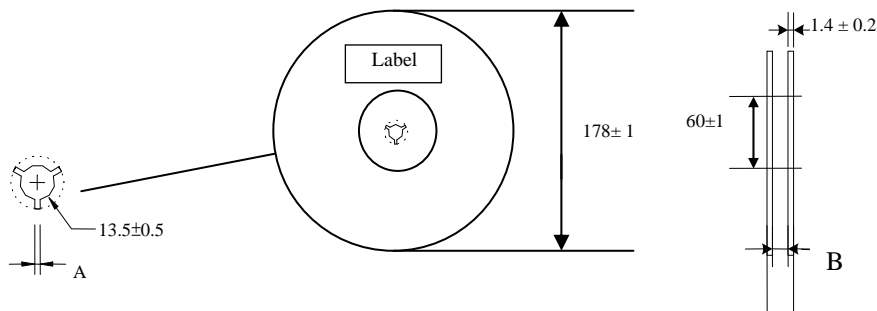
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0± 0.1	4.0± 0.1	1.10± 0.1	1.92± 0.1	2.0± 0.1	3.5± 0.1	8.0± 0.1	0.75± 0.05	4,000pcs	Paper

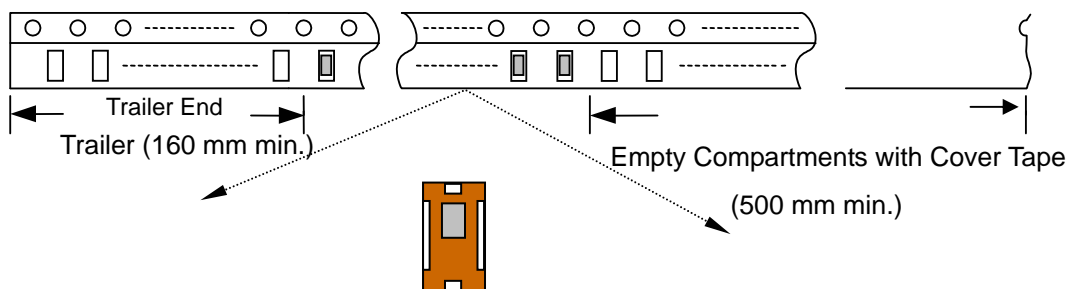
❖Reel Dimensions (Unit: mm)



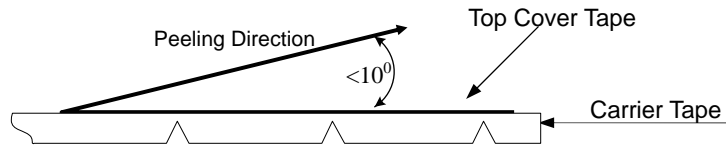
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

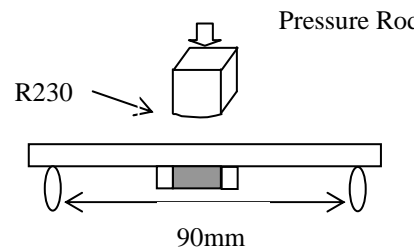
❖ **Storage Conditions**

- (1) Temperature: 15 ~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

Notes

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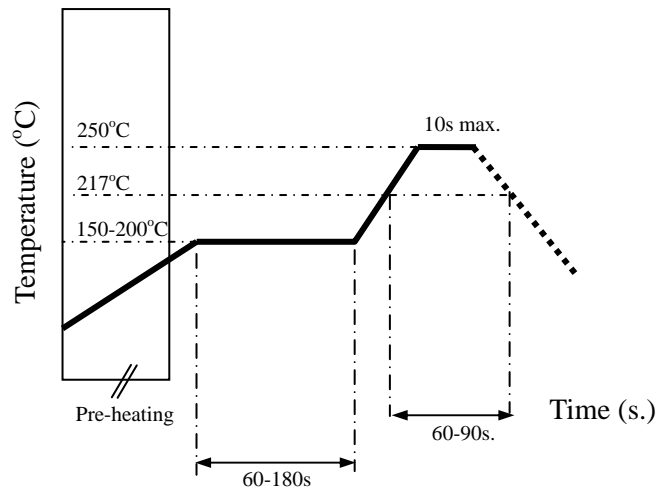
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 75% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 1kg minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection (Chip length <4.5mm) 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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Advanced Ceramic X Corp.

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: acx@acxc.com.tw

<http://www.acxc.com.tw>